

**ABSTRACT OF THE DISCLOSURE**

A microcomputer heat dissipation system comprising heat-absorbing units, wherein said heat-absorbing units can be bonded to heat-generating electrical components inside the microcomputer and are in communication with a fluid circulating unit, and, to said fluid-circulating unit, there can be serially connected at least a heat-radiating pipe bondable to a heat-radiating plate, with said heat-radiating plate disposed on the outer wall surface of the chassis. In this manner, most of the heat generated by the microcomputer is dissipated to the space outside of the microcomputer, and, at the same time, the elimination of the internal fans of the microcomputer permits a considerable reduction in the acoustic noise level during operation of the microcomputer.

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